

Product Change Notification - JAON-29FZGD903

Date:

21 Nov 2018

Product Category:

Linear Regulator ICs

Affected CPNs:

7

Notification subject:

CCB 2774 Final Notice: Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using CRM-1800 die attach material.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using CRM-1800 die attach material.

Pre Change:

Assembled at GEMC assembly site using 84-1LMISR4 die attach material

Post Change:

Assembled at GTBF assembly site using CRM-1800 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Gem (GEMC)	Great Team Backend Foundry				
	Geili (GEMC)	(Dong Guan) Ltd. (GTBF)				
Wire material	Au wire	Au wire				
Die attach material	84-1LMISR4	CRM-1800				
Molding compound material	G600	G600				
Lead frame material	PMC90	PMC90				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTBF assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

December 21, 2018 (date code: 1851)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:



	December 2016			->	November 2018					December 2018					
Workweek	48	49	50	51	52		44	45	46	47	48	49	50	51	52
Initial PCN Issue Date		Х													
Qual Report										V					
Availability										^					
Final PCN Issue Date										Х					
Estimated														Х	
Implementation Date														^	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 6, 2016: Issued initial notification.

November 21, 2018: Issued final notification. Attached the qualification. Provided estimated first ship date to be on December 21, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-29FZGD903_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

CL220K4-G CL2K4-G CL520K4-G CL525K4-G CL6K4-G LR12K4-G LR8K4-G